

4 / MAP

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 , *Huvis R&D , **
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Studies on Cure Behavior and Rheological Properties of Tetrafunctional Epoxy/Biodegradable MAP Blends

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: 4 (4EP) modified aliphatic polyester (MAP)
 , , DSC
 (E_a) 4EP MAP 10 wt% 가 가 .
 4EP MAP 가 MAP 가 10 30 wt%
 (E_t) Coats - Redfern 가 가 .
 가 . Arrhenius
 가 (E_c) , E_a
 (K_{IC}) semi - IPN .

ABSTRACT : In this work, biodegradable modified aliphatic polyester (MAP) in tetrafunctional epoxy (4EP) resin was investigated in terms of cure kinetics, thermal stabilities, rheological properties, and mechanical interfacial properties. DSC results of the blends show that the cure activation energies (E_a) were increased in 10 wt% of MAP compared with neat 4EP, due to the increasing intermolecular interaction between 4EP and MAP. The decomposed activation energies (E_t) derived from Coats - Redfern method, were increased within the 10 30 wt% composition range of MAP contents, resulting from increasing the cross - linking density of the blend system. Rheological properties of the blend system were investigated under isothermal condition using a rheometer. Cross - linking activation energies (E_c) were determined from the Arrhenius equation based on gel time and curing temperature. As a result, the E_c showed a similar behavior with E_a. The fracture toughness (K_{IC}) of the mechanical interfacial properties was discussed in semi - IPN behaviors of the casting specimen.

Keywords : *tetrafunctional epoxy resin, cure kinetics, thermal stabilities, rheological properties, mechanical interfacial properties.*

diglycidyl ether of bisphenol A(DGEBA)

tetrafunctional epoxy(4EP)

4EP

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in - situ

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4EP

7,8

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4EP

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가

4EP

MAP

4,4' - diamino diphenyl

methane (DDM)

DSC TGA

K_{IC}

4EP LG LER 430 (8000

14000 cps, E. E. W=110 130 g/eq)

, modified aliphatic polyester (MAP) Huvis

4,4' - DDM (=89 91 , = 49.5)

LER 430, MAP,

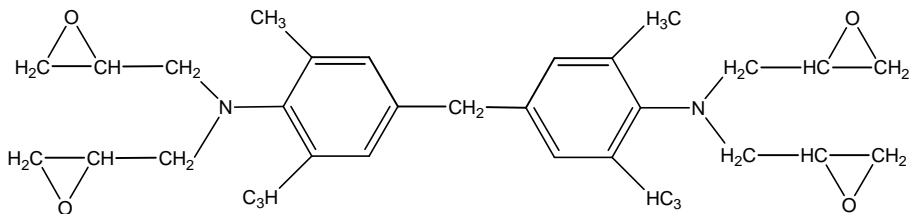
DDM Figure 1

4EP (DDM) 1:1

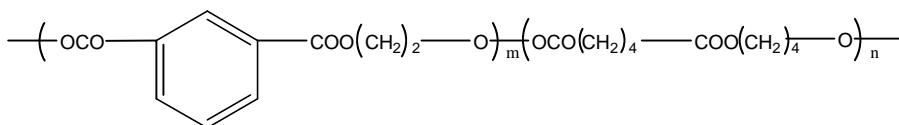
, 4EP MAP 100:0,

90:10, 80:20, 70:30, 60:40 wt%

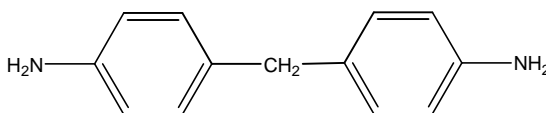
MAP dichloromethane (CH₂Cl₂)



LER 430 (viscosity: 8,000~14,000 cps, E.E.W=110~130 g/eq)



MAP (modified aliphatic polyester)



4,4' - diaminodiphenyl - methane (DDM)

Figure 1. Chemical structures of (a) 4EP, (b) MAP, and (c) DDM.

70 4EP 10 /min, (T_{max}),
 80 가
 4EP/MAP/DDM 4EP/MAP/DDM
 (differential scanning calor- 가 가
 imeter, DSC) Perkin Elmer DSC - 6
 DSC damping factor (tanδ)
 scan Rheolab MC100
 0.5 mm, 5 Hz
 2, 5, 10, 20 /min
 DSC 100, 115, 130
 (α) (dα/dt) (K_{IC}) K_{IC}
 4EP/MAP/DDM single edge notched bending (SENB) ASTM
 convection oven 70 (30 E399 1/2
 min), 140 (2 h) 200 (1 h) cross - head speed 1 mm/min, span - to - depth
 (Dupont, TGA - ratio 4:1
 2950) 30 800 SEM

Figure 2 4EP/MAP
 DSC 가 150 가 MAP 가
 DSC 가 MAP 가
 half - width Half - width half - height (E_a) half - height half - width 가 Arrhenius (1)

$$k = A \exp(-E_a / RT) \quad (1)$$

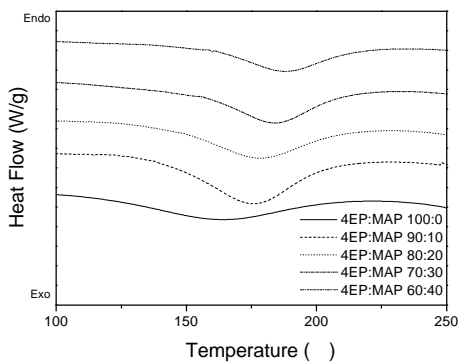


Figure 2. Dynamic DSC thermograms for different 4EP/MAP compositions (10 °C/min).

$$\ln t_{1/2} = E_a / RT - \ln A \quad (2)$$

, t_{1/2} half - width time, A , E_a , R T
 (2) Int t_{1/2} vs. 1/T
 E_a Figure 3
 E_a 4EP MAP 10 wt% MAP 가
 가 10 wt% 가 가
 E_a가 가
 가

DSC H_t
 Figure 4 4EP/MAP
 가

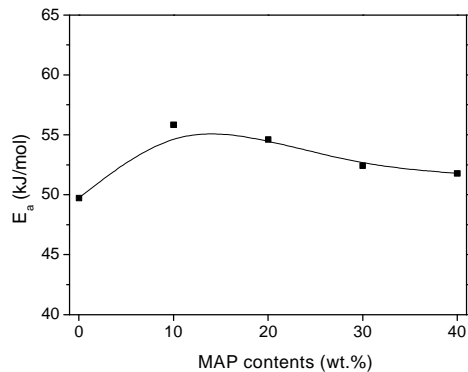


Figure 3. Cure activation energy (E_a) for different MAP contents.

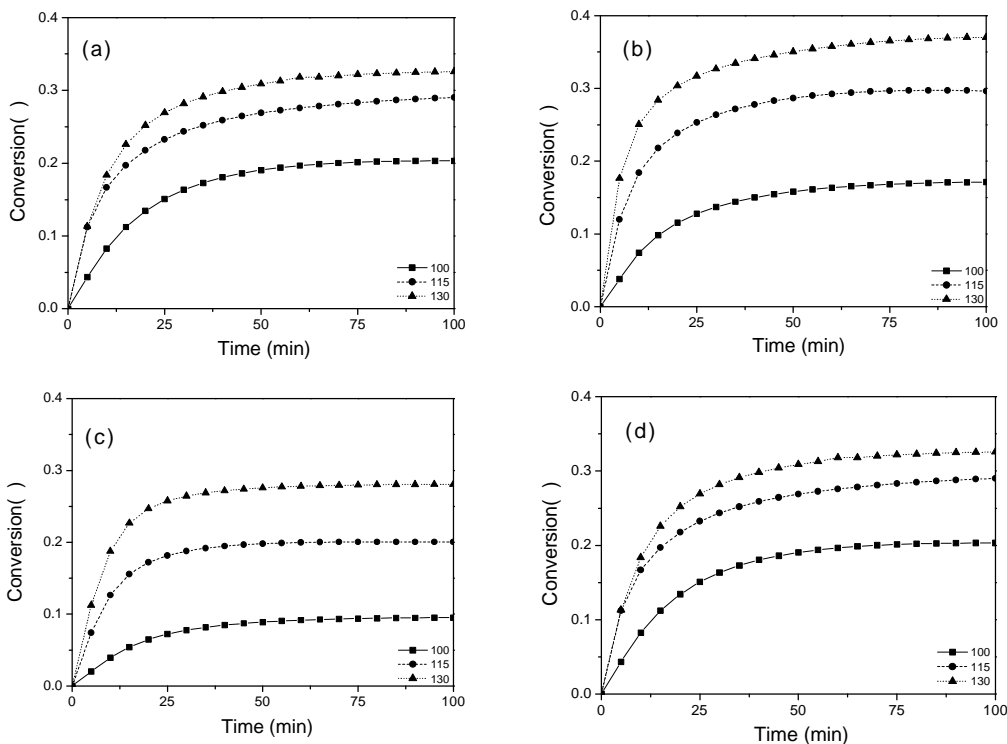


Figure 4. Conversion as a function of time at different temperatures : (a) MAP 0 wt%, (b) MAP 10 wt%, (c) MAP 20 wt%, and (d) MAP 40 wt%.

Figure 5

MAP 10 wt%

MAP

10 wt%

MAP

4EP

MAP

Figure 5

MAP

10 wt%

10 wt%

Figure 6

TGA

4EP/MAP (IPDT),

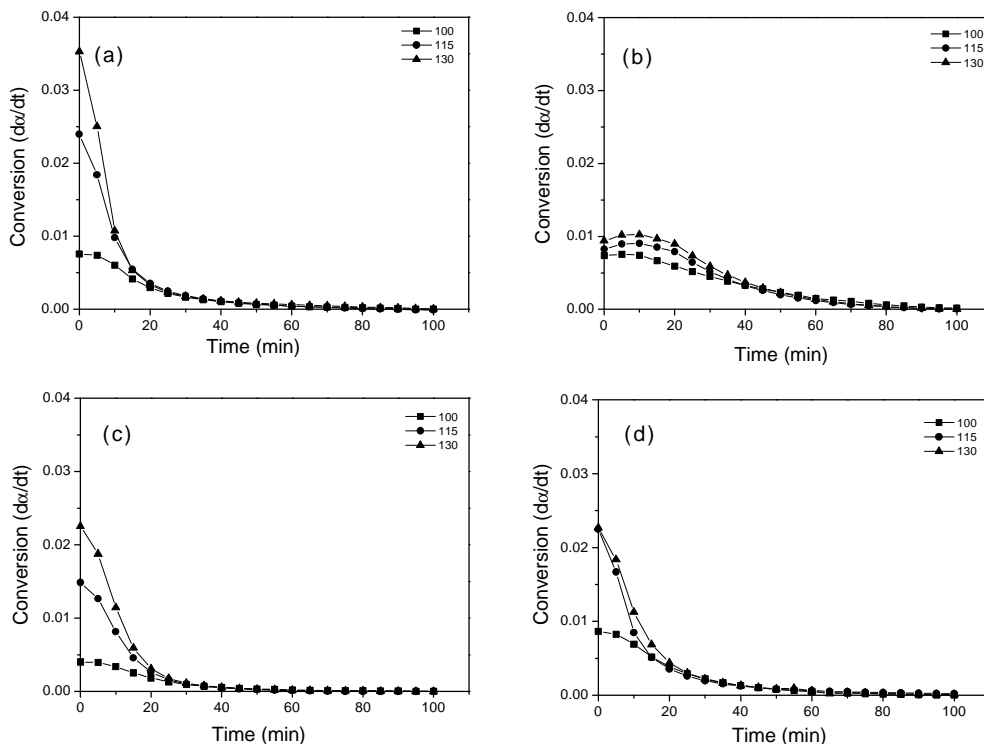


Figure 5. Conversion rate as a function of time at different temperatures : (a) MAP 0 wt%, (b) MAP 10 wt%, (c) MAP 20 wt%, and (d) MAP 40 wt%.

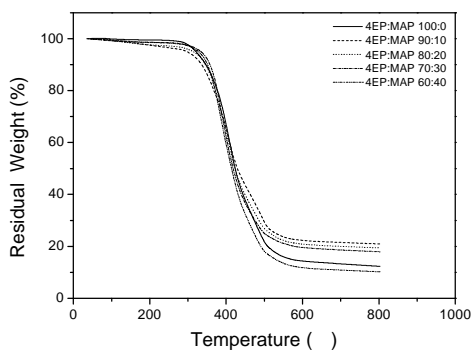


Figure 6. TGA thermograms of 4EP/MAP blends.

Table 1. Thermal Stabilities of 4EP/MAP Blend System

composition [4EP/MAP]	IPDT []	T _{max} []	A* · K*	IDT []
100:0	597	403	0.69	256
90:10	755	407	0.89	277
80:20	728	406	0.86	248
70:30	698	388	0.82	281
60:40	556	386	0.64	273

(temperature of maximum weight loss, T_{max}), (A* · K*), (initial decomposition temperature, IDT) Table 1¹³ (thermogravimetric analysis, TGA) Table 1

IPDT A* · K* 4EP
 MAP 10 wt% 가
 , 20, 30 , 40 wt%

semi-IPN¹⁴ MAP 10 wt%
 MAP 가 가 가 가 가 가

4 / MAP

가
 15
 Coats - Redfern
 Figure 6 4EP/MAP
 thermogram
 (a) (T_{max})

(E_t) ln(α/T²) vs. 1/T
 (linear fitting)

$$\ln(a/T^2) = \ln(AR/bE_t)[1 - (2RT/E_t)] - (E_t/RT) \quad (3)$$

A, b dt/dT,
 E_t, T

R Figure
 6 thermogram ln(α/T²) 1/T

Figure 7 E_t 3 가

가 가
 Figure 7 E_t 10 wt%
 가 가 가
 MAP가 semi -
 IPN MAP 4EP가 가
 E_t가

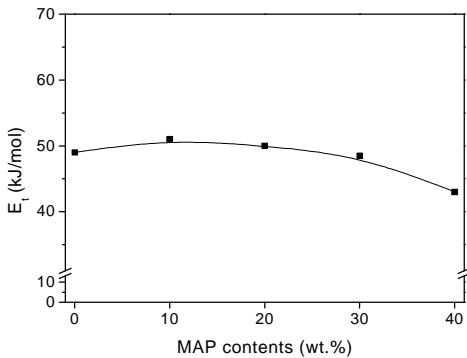


Figure 7. Decomposed activation energies (E_t) for different MAP contents.

(G')
 (G'')

가 .17

가

가

가

.18

G'

가 G''

Figure 8

가

G' G''

Tung Dynes¹⁹
 (tanδ=1)
 (4)

3

가 가

.20

$$\tan d = \frac{G''}{G'} = \tan(np/2) \quad (4)$$

Figure 8 120 4EP/MAP

G' G''

G'

G''

가

, MAP 10 wt%

4EP

MAP가 가

, 40 wt%

4EP

가

MAP

가

MAP

Figure 9 Figure 8

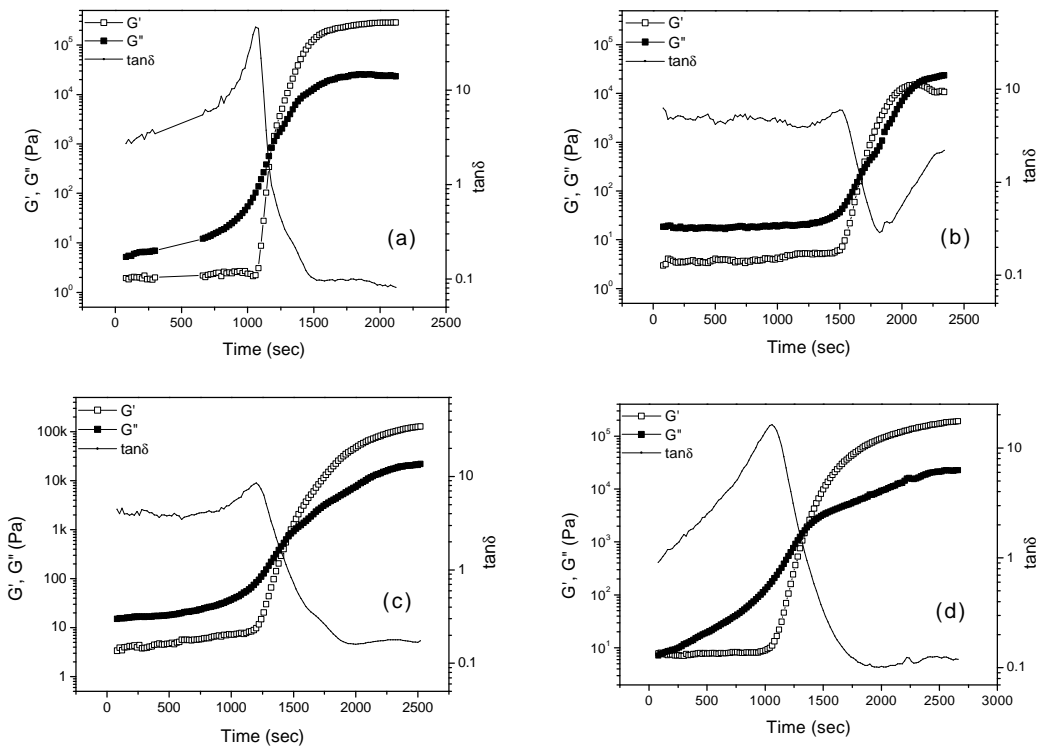


Figure 8. Plots of G' , G'' , and $\tan\delta$ at 120 for 4EP/MAP : (a) 100:0, (b) 90:10, (c) 80:20, and (d) 60:40.

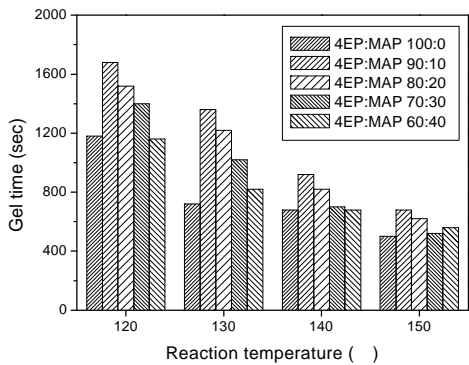


Figure 9. Gel times of 4EP/MAP blend system.

$$\ln t_c = \left[\ln \left(\int_0^{a_c} \frac{da}{f(a)} \right) - \ln A \right] + E_c / RT \quad (5)$$

$$\ln t_c = \frac{E_c}{RT} + C \quad (6)$$

Figure 10

Figure 11 E_c . E_c
 , MAP가 10 wt% E_c
 가 , 10 wt%
 4EP 가 MAP 가 ,
 MAP 가 4EP MAP가
 가 가
 E_c 가 . E_c
 E_a , 가

4EP/MAP
 (crack growth resistance)
 (critical stress intensity fac-

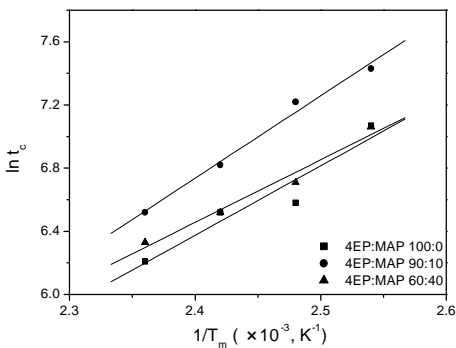


Figure 10. Plots of gel time vs. curing temperature for different 4EP/MAP compositions.

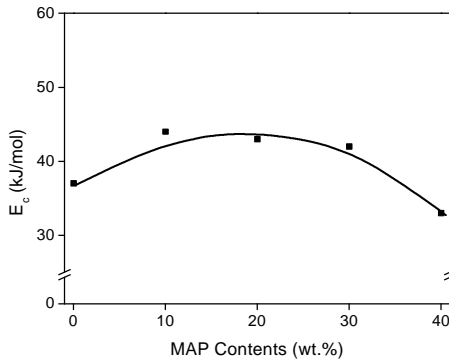


Figure 11. Cross - linking activation energy(E_c) for different MAP contents.

tor, K_{IC} (6)
^{23,24}

$$K_{IC} = \frac{P \cdot L}{b \cdot d^{3/2}} \cdot Y \quad (6)$$

, P , L span , b
 , d , Y ,
 , geometric factor

(7)

$$Y = \frac{3(a/b)^{1/2}[1.99 - (a/b)(1 - a/b)\{2.15 - 3.93(a/b) + 2.7(a/b)^2\}]}{2[1 + 2(a/b)\{1 - (a/b)^{3/2}\}]} \quad (7)$$

Figure 12 4EP/MAP K_{IC}
 , MAP 10 wt% 가
 MAP 10 wt% semi - IPN
 MAP 가

Figure 13 4EP/MAP SEM
 , 4EP
 MAP 10 wt%가 가

MAP가 가 semi - IPN 가

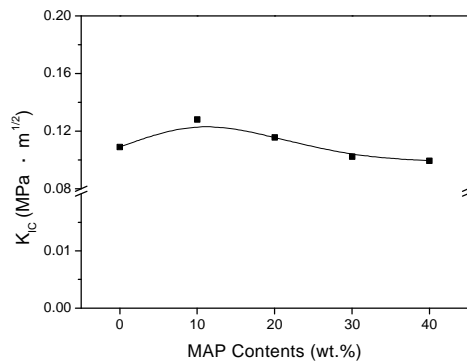


Figure 12. K_{IC} for different MAP contents.

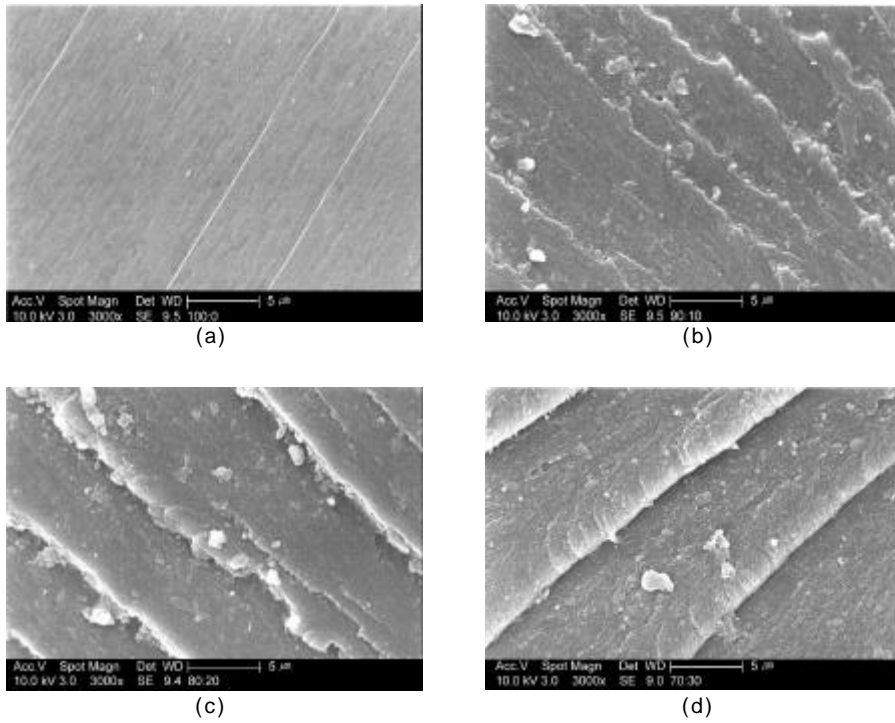


Figure 13. SEM photographs of fracture surfaces for 4EP/MAP blend system : (a)100:0, (b) 90:10, (c) 80:20, and (d) 70:30.

DDM 4EP/MAP
 100:0 60:40 wt%

DSC DDM
 150 4EP E_a
 10 wt% 가 가 가

가 가 DSC
 10 wt% 가 가

IDT, E_t TGA IPDT, T_{max}
 MAP

10 wt% 가 , 10 wt%

가 , 가
 4EP/MAP K_{IC} , 10 wt%

가

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